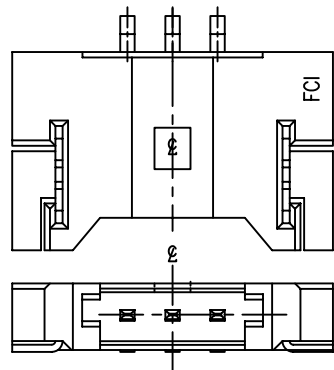
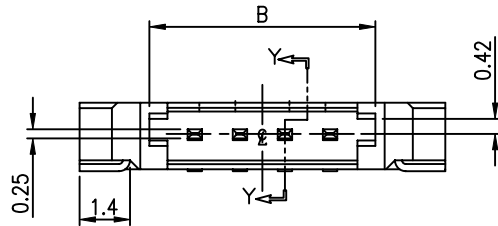
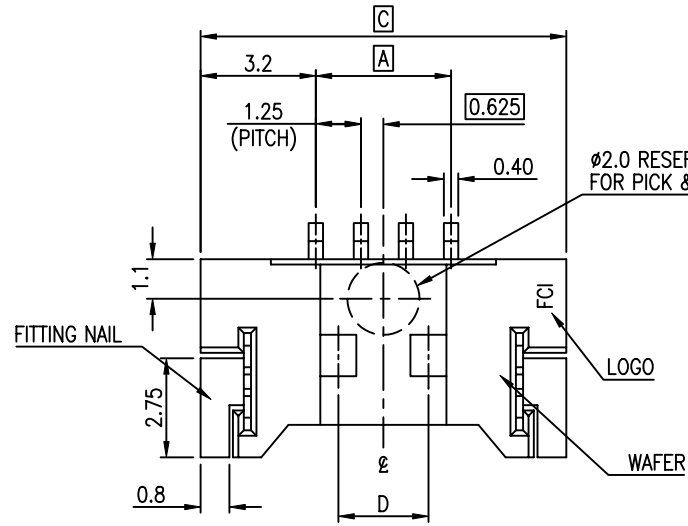
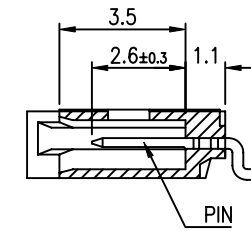
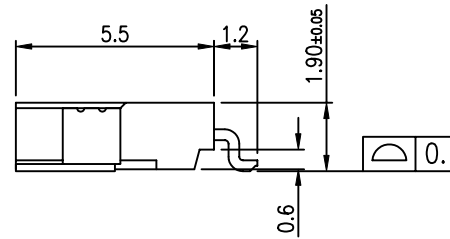
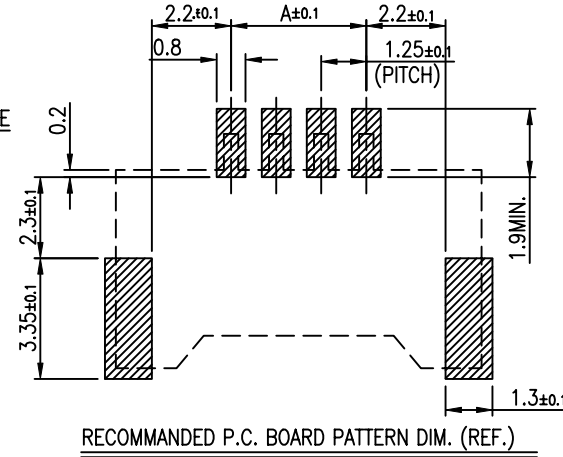




FOR 2 & 3 PIN

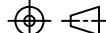


SECT. Y-Y

- NOTES:
- MATERIAL:
 - 1.1 HOUSING: HIGH TEMP THERMOPLASTIC,UL94V-0.
 - 1.2 CONTACT: COPPER ALLOY
 - 1.3 FITTING NAIL: COPPER ALLOY
 - FINISH:
 - UNDER PLATING: 50u" MIN. NICKEL OVERALL
 - CONTACT AREA AND SOLDER TAIL: GOLD FLASH 1u" MIN. OVERALL
 - FITTING NAIL:
 - UNDER PLATING: 50u" MIN. NICKEL OVERALL
 - GOLD FLASH 1u" MIN. OVERALL
 - REFLOW SOLDER CAPABLE TO 260°C PEAK TEMP. FOR 10 SECONDS MAX.
 - SPEC. PLS. REFER TO GS-12-573.
 - PACKAGE PLS. REFER TO GS-14-1315.
 - PART NUMBER DESCRIPTION:
 - 10089716-XXX 0 0 0 LF
 - LEAD FREE
 - COLOR
 - 0: NATURAL
 - PLATING
 - 0: GOLD FLASH

NO. OF CONTACTS
PACKING
0: TAPE & REEL

CKT	Dim.A	Dim.B	Dim.C	Dim.D
002	1.25	3.77	7.65	--
003	2.50	5.02	8.90	--
004	3.75	6.27	10.15	2.50
005	5.00	7.52	11.40	3.75
006	6.25	8.77	12.65	5.00
009	10.00	12.52	16.40	8.75

mat'l. code				tolerances unless otherwise specified			CUSTOMER COPY		FCI 		www.fciconnect.com			
ltr	ecn no	dr	date	linear	.X ± 0.25			projection 	title 1.25mm WIRE TO BOARD WAFER SMT R/A TYPE					
A	T08-1164	WL	08/11/08		.XX ± 0.15									
B	T08-1185	WL	11/13/08		.XXX ± 0.10									
C	T08-1196	WL	12/10/08	angles	0° ± 2°				product family WTB size dwg no 10089716					
D	T09-1001	WL	01/05/09	dr	LEIF SHEN	06/18/08	scale							
E	T09-1005	WL	01/20/09	enr	LEIF SHEN	06/18/08								
F	T09-1077	WL	06/05/09	chr	LEIF SHEN	06/18/08								
				appd	JOSEPH HSIA	06/18/08		A4	sheet 1 of 1					
sheet index	revision sheet		F 1											